



## Product End-of-Life Disassembly Instructions

**Product Category: Notebooks**

**Marketing Name / Model**  
**[List multiple models if applicable.]**

HP Pavilion 13 Laptop PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPI products to remove components and materials requiring selective treatment, as defined by EU directive 2012/19/EC, Waste Electrical and Electronic Equipment (WEEE).

NOTE: Recyclers should sort plastic materials into resin streams for recycling based on the ISO 11469 plastic marking code on the plastic part. For any questions on plastic marking, please contact [HP's Sustainability Contact](#).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	
Batteries, excluding Li-Ion batteries.	All types including standard alkaline, coin or button style batteries	
Li-Ion batteries. Include all Li-Ion batteries if more than one is provided with the product (such as a detachable notebook keyboard battery, RTC coin cell, etc.)	Battery(ies) are attached to the product by ( <i>check all that apply with an "x" inside the "[ ]"</i> ): [x] screws [x] snaps [0] adhesive [0] other. Explain _____ NOTE: Add detailed removal procedures including required tools in the sections 3.1 and 3.2.	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords	DC Cable for External Power Supply	1
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs)		

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Page 1

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HPI instructions for this template are available at [EL-MF877-01](#)

Item Description	Notes	Quantity of items included in product
already listed as a separate item above)		
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	#0,#1

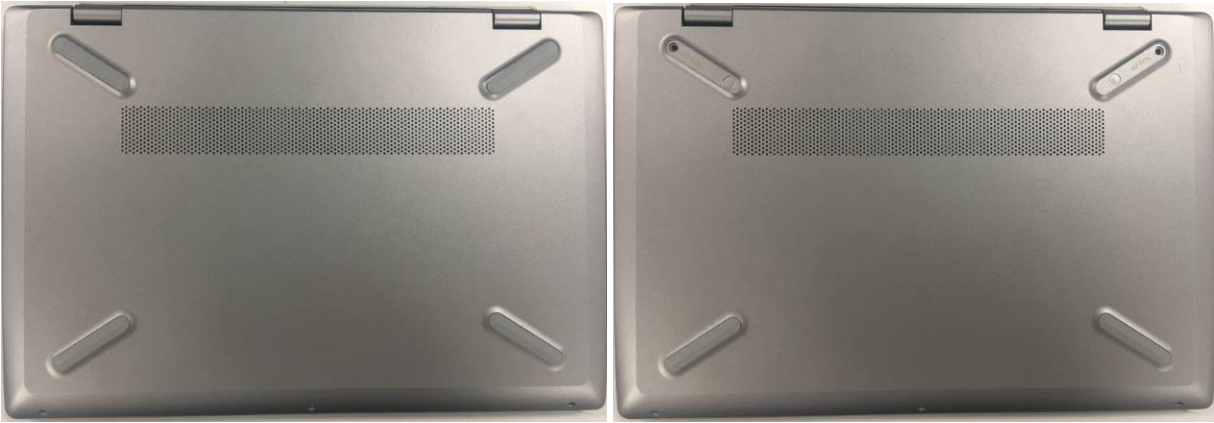
## 3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment including the required steps to remove the external enclosure:

1. Remove rear side rubber foot and dis-fasten BASE screw\*5
2. Remove BASE and dis-fasten battery screw\*6;thermal module screw\*3; fan module screw\*6 D/B screw\*4 M/B screw\*4 speaker screw\*2 hinge L screw\*3 hinge R screw\*3
3. Next remove battery, HDD, M/B, speaker, and LCD assy
4. Remove LCD bezel and pull out disposable adhesive then remove panel
5. Dis-fasten hinge L screw\*4 and hinge R screw\*4 and remove hinge L and R and remove Panel, Hinge, LCD cable and antenna

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

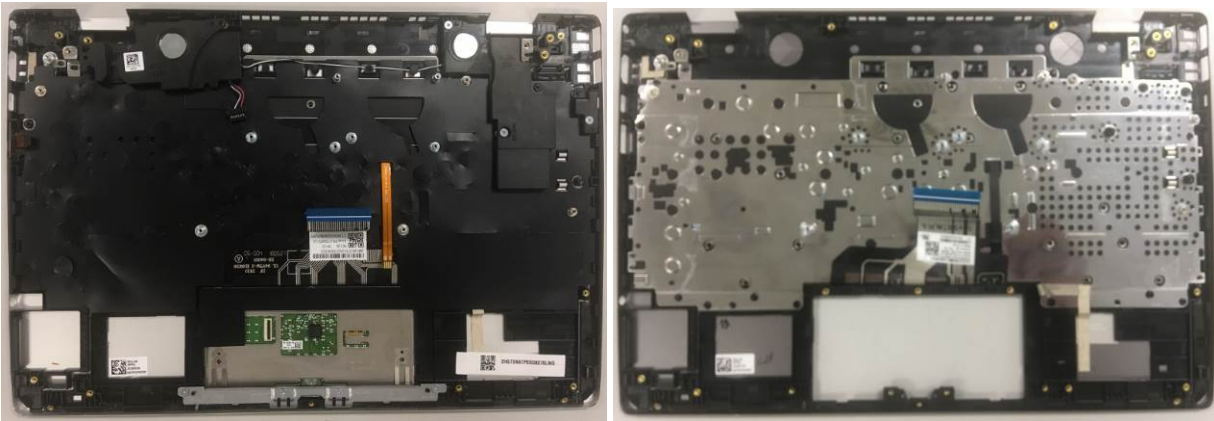
1. Remove rear side rubber foot and dis-fasten BASE screw\*5



2. Remove BASE and dis-fasten battery screw\*6;thermal module screw\*3; fan module screw\*6 D/B screw\*4 M/B screw\*4 speaker screw\*2 hinge L screw\*3 hinge R screw\*3



3. Next remove battery, HDD, M/B, speaker, Touch pad and LCD assy



4. Remove LCD bezel and pull out disposable adhesive then remove panel



5. Dis-fasten hinge L screw\*4 and hinge R screw\*4 and remove hinge L and R and remove Panel, Hinge, LCD cable and antenna

